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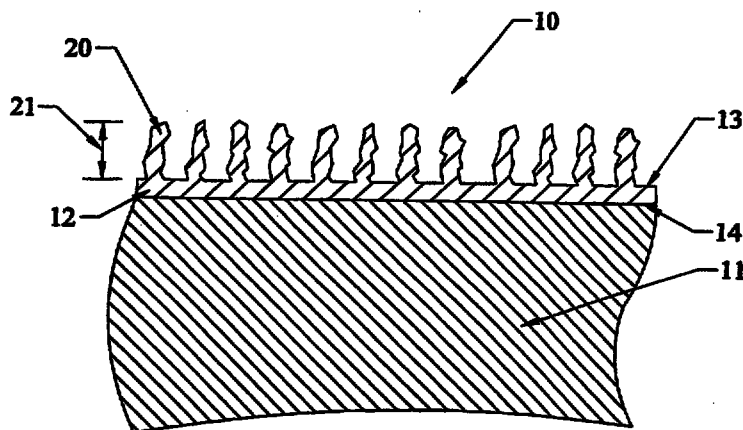
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- (71) Applicant (for all designated States except US): **MICRO-COATING TECHNOLOGIES, INC. [US/US];** 5315 Peachtree Industrial Boulevard, Chamblee, GA 30341 (US).
- (74) Agents: **MURATORI, Alfred, H. et al.;** MicroCoating Technologies, Inc., 5315 Peachtree Industrial Boulevard, Chamblee, GA 30341 (US).
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(54) Title: **NANOSTRUCTURE COATINGS**



(57) Abstract: A thin film product having a nanostructured surface, a laminate product including the thin film and a temporary substrate opposite the nanostructured surface, a laminate product including the thin film and a final substrate attached to the nanostructured surface and a method of producing the thin film products. The thin film is particularly useful in the electronics industry for the production of integrated circuits, touch screen, flat panel display, printed circuit boards and EMF shielding. The nanostructured surface includes surface features that are mostly smaller than one micron, while the dense portion of the thin film is between 10-200nm. The thin film is produced by coating a temporary substrate (such as aluminum foil) with a coating material (such as copper) using any process. One such method is concentrated heat deposition or a combustion, chemical vapor deposition process. The resulting thin film provides a high level of adhesion to a final substrate, by embedding the nanostructures with the material of the final substrate (such as epoxy resin). The surface of the thin film adjacent the temporary substrate substantially conforms to the substrate surface and has a relatively low peel strength. In this manner, the temporary substrate is easily removed from the thin film after attaching the opposite nanostructured side of the thin film to the final substrate with a resulting, higher peel strength.

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